



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20150325000
Topside symbol change for CC3100/3200 Devices
to correct the ECAT classification to G4
Information Only**

Date: 3/31/2015
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20150325000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CC3100R11MRGC	null
CC3200R1M1RGC	null
CC3200R1M2RGC	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150325000	PCN Date:	03/31/2015
Title:	Topside symbol change for CC3100/3200 Devices to correct the ECAT classification to G4		
Customer Contact:	PCN_ww_admin_team@list.ti.com	Dept:	Quality Services
Change Type:	Device Marking		
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Informational notification to announce a topside symbol change for CC3100/3200 Devices to correct the ECAT classification to G4.			
Reason for Change:			
The current symbolization erroneously identifies the ECAT classification as G3, it will be corrected to show G4. There is no change in material, just the ECAT classification being corrected.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
Sample Device Marking:			
Change From:			
O {CUST1} \T/ YMS XLLL G3	CUST1 = TI Device Identifier \T/ = TI logo YM = Year/Month LLLL = Lot Trace Code S = Primary Site Code X = Secondary Site Code G3 = Jedec Terminal Finish Matte Sn O = Pin 1		
Change To:			
O {CUST1} \T/ YMS XLLL G4	CUST1 = TI Device Identifier \T/ = TI logo YM = Year/Month LLLL = Lot Trace Code S = Primary Site Code X = Secondary Site Code G4 = Jedec Terminal Finish NiPdAu O = Pin 1		

Sample Product Shipping Label (not actual product label)

Assembly Site

Amkor P3	Assembly Site Origin (22L)	ASO: AP3	ECAT:G3
Amkor P3	Assembly Site Origin (22L)	ASO: AP3	ECAT:G4

Sample product shipping label to show code location only (not actual product label)

Product Affected:

CC3200R1M2RGC	CC3200R1M2RGCR	CC3200R1M1RGCR	CC3200R1M1RGC
CC3100R11MRGCR	CC3100R11MRGC	XCC3200R1M2RGC	XCC3200R1M2RGCT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com